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Semiconductor devices –

Part 16-1: Microwave integrated circuits – Amplifiers

Dispositifs à semiconducteurs –

Partie 16-1: Circuits intégrés hyperfréquences – Amplificateurs

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –**Part 16-1: Microwave integrated circuits – Amplifiers**

FOREWORD

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International Standard IEC 60747-16-1 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47E/200/FDIS	47E/204/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2004. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this standard may be issued at a later date.

SEMICONDUCTOR DEVICES –

Part 16-1: Microwave integrated circuits – Amplifiers

1 Scope

This part of IEC 60747 provides the terminology, the essential ratings and characteristics, as well as the measuring methods for integrated circuit microwave power amplifiers.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 60747. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this part of IEC 60747 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 60617-12:1997, *Graphical symbols for diagrams – Part 12: Binary logic elements*

IEC 60617-13:1993, *Graphical symbols for diagrams – Part 13: Analogue elements*

IEC 60747-1:1983, *Semiconductor devices – Discrete devices – Part 1: General*

IEC 60747-7:2000, *Semiconductor devices – Part 7: Bipolar transistors*

IEC 60748-2:1997, *Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits*

IEC 60748-3:1986, *Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits*

IEC 60748-4:1997, *Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits*